

Taiwan Semiconductor

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	R _{OJL}	12	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	47	°C/W

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	I _F = 3A, T _J = 25°C	V _F	-	0.9	V
Reverse current @ rated V _R ⁽²⁾	T _J = 25°C	I _R	-	5	μΑ
	T _J = 125°C		-	150	μΑ
Junction capacitance	1MHz, V _R = 4.0V	CJ	45	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	20	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
ESH3x	DO-214AB (SMC)	3,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 100V(ESH3B) to 200V(ESH3D)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

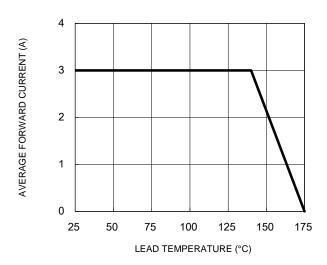


Fig.3 Typical Reverse Characteristics

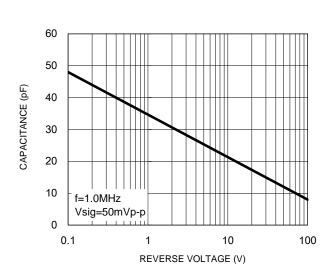
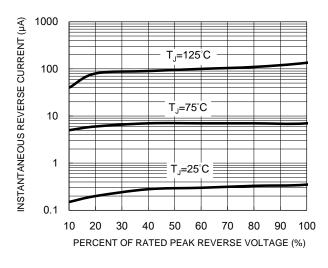


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



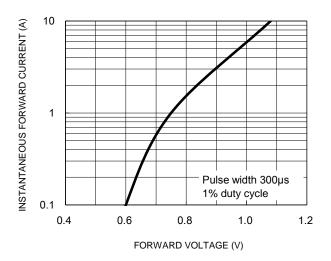
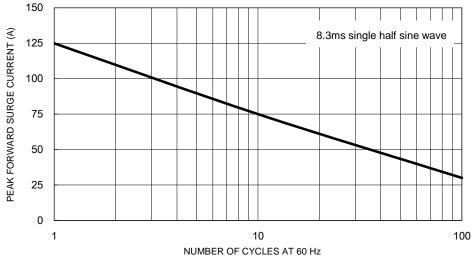


Fig.5 Maximum Non-Repetitive Forward Surge Current



3

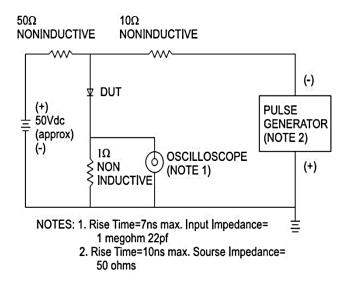


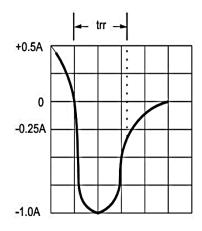


CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram



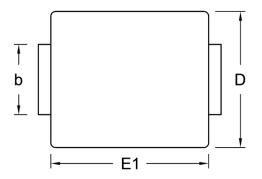


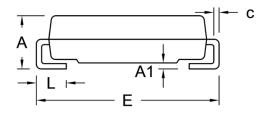




PACKAGE OUTLINE DIMENSIONS

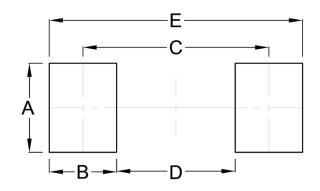
DO-214AB (SMC)





DIM.	Unit (mm)		Unit ((inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	2.00	2.62	0.079	0.103
A1	0.10	0.20	0.004	0.008
b	2.90	3.20	0.114	0.126
С	0.15	0.31	0.006	0.012
D	5.59	6.22	0.220	0.245
E	7.75	8.13	0.305	0.320
E1	6.60	7.11	0.260	0.280
L	1.00	1.60	0.039	0.063

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



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